

ABSTRACT

A plurality of printed boards are stacked and collectively pressed to be manufactured into a multilayer circuit board. An outermost conductor layer is stacked on an insulating layer side of a first outermost printed board disposed with the insulating layer side being directed outward, and pressed. A conductor layer of a second outermost printed board disposed with the conductor layer side being directed outward is previously formed with no conductor circuit and pressed under a condition where the conductor layer has a uniform thickness throughout. Consequently, manufacturing steps can be simplified and the precision of the multilayer circuit board can be improved.

I:\ATTY\QM\21's\217883\US\Sub SPEC-CLEAN COPY.DOC